



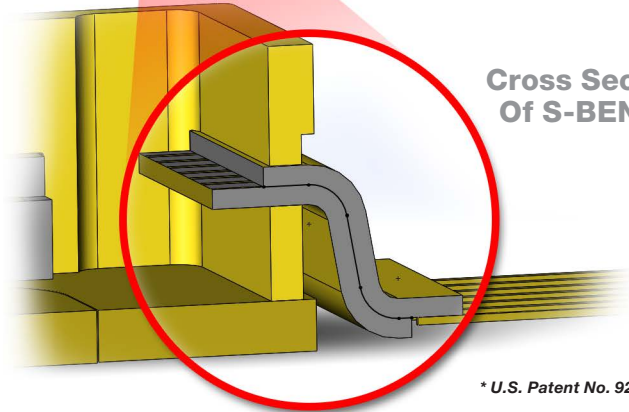
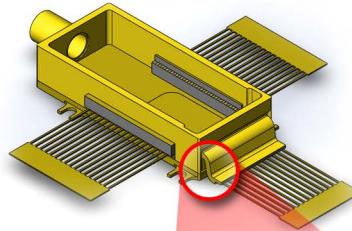
S-Bend Ceramic Feedthru*

FOR HIGH SPEED TRANSMISSION

- ▲ Alpha performance > 35 GHz
- ▲ Beta designs intended to reach 50 GHz
- ▲ Smooth uninterrupted RF signal path
- ▲ No vias in signal path
- ▲ No 90° via transitions
- ▲ Reduced reflection coefficient
- ▲ Reduced return loss
- ▲ Reduced transmission loss
- ▲ Increased bandwidth performance

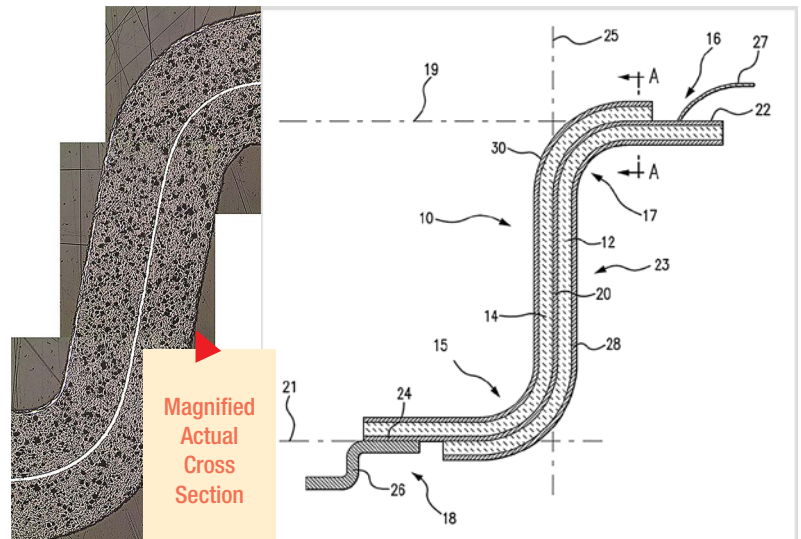
AMETEK's **S-Bend Ceramic Feedthru** provides a high frequency interconnect advantage by eliminating 90 degree transitions (vertical vias and stair-step vias) used in conventional feedthrough designs. The S-Bend design eliminates the RF reflection caused by 90 degree via transitions. A bandwidth performance increase is achieved as the result of the reduced reflection coefficient (no via transitions) and offers the related benefits of reduced return loss and reduced transmission loss.

The unique design of the **S-Bend Ceramic Feedthru** provides a hermetic interconnect solution for high speed application in a structurally robust form factor. The "S" shape provides the critical transition of the RF/Microwave signal from the wire bond pads inside the package to the output leads on the outside of the package without the use of vias. This design provides an uninterrupted signal path and allows for improved electrical performance without vias, as compared to traditional feedthrough designs.



Cross Section
Of S-BEND

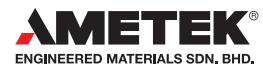
* U.S. Patent No. 9277643



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